

S-394-MG

Micronized Wax

Shamrock's product line of micronized waxes provide rub and abrasion resistance. Included in this line are products that provide gloss, matting, clarity, and controlled slip in a range of particle sizes.

Product Description:

S-394-MG is a synthetic wax with a DSC melt peak above 110°C.

Application:

S-394-MG is recommended for liquid and paste inks. S-394-MG is also recommended for use in many types of coating systems including solvent-based, water-based, UV, and powder coatings.S-394-MG can be used for both pigmented and clear compositions. S-394-MG is recommended at 2-3% of total formula weight for slip and abrasion resistance and 5-10% for matting.

Features and Benefits:

Good Abrasion Resistance

Good Slip

Assists in Matting

Typical Properties:

Specific Gravity: 0.95 g/cm³
Particle Size Mean Value: 5 μm
99% of Particle Under: 12 μm
NPIRI Grind: 2.5 max
Hegman Grind: 6.5 min
Melting Point: 230/110 °F/°C

Regulatory Status:

The components of this product are listed on multiple chemical inventories. For specific information on the applicable chemical inventories, please refer to the product SDS. This product meets the requirements of 21 CFR 175.105, 175.250, 175.300, 175.320, 176.170, and 176.180.

Safety, Shipping and Handling:

For complete safety, shipping and handling information please contact your regional Customer Service Representative, or our Customer Service Team at customerserviceteam@shamrocktechnologies.com.

For **more** information about Shamrock's other products or capabilities please visit us at our website, ShamrockTechnologies.com.

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